

10/086, 875

L Number	Hits	Search Text	DB	Time stamp
-	434	(carrier interposer) and power and ground and (conductive adj adhesive) and @ad<19990719	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/16 23:23
-	330	((carrier interposer) and power and ground and (conductive adj adhesive) and @ad<19990719) and substrate		2002/11/16 23:23
-	29	(carrier interposer) and power and ground and (conductive adj adhesive adj layer) and @ad<19990719		2002/11/16 23:25
-	23	((carrier interposer) and power and ground and (conductive adj adhesive adj layer) and @ad<19990719 ) and signal		2002/11/16 23:25